## **Dual General Purpose Transistor**

The MBT3906DW1 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-363 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

#### **Features**

- h<sub>FE</sub>, 100-300
- Low  $V_{CE(sat)}$ ,  $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7-inch/3,000 Unit Tape and Reel
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	-40	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	-40	Vdc
Emitter – Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current - Continuous	Ic	-200	mAdc
Electrostatic Discharge	ESD	HBM Class 2 MM Class B	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Package Dissipation (Note 1) T <sub>A</sub> = 25°C	P <sub>D</sub>	150	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	833	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.



### ON Semiconductor®

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### MARKING DIAGRAM



SOT-363/SC-88 CASE 419B STYLE 1



XX = Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

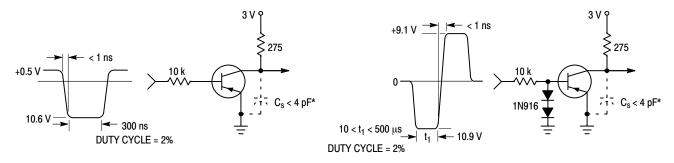
See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTE	RISTICS				1	
Collector - Emitter	Breakdown Voltage (Note 2)	V <sub>(BR)CEO</sub>	-40	-	Vdc	
Collector - Base Br	reakdown Voltage	V <sub>(BR)</sub> CBO	-40	-	Vdc	
Emitter – Base Brea	akdown Voltage	V <sub>(BR)EBO</sub>	-5.0	-	Vdc	
Base Cutoff Currer	nt	I <sub>BL</sub>	_	-50	nAdc	
Collector Cutoff Cu	ırrent	I <sub>CEX</sub>	-	-50	nAdc	
ON CHARACTER	RISTICS (Note 2)					
$(I_C = -1.0 \text{ mAdc},$ $(I_C = -10 \text{ mAdc},$ $(I_C = -50 \text{ mAdc},$	, V <sub>CE</sub> = -1.0 Vdc) , V <sub>CE</sub> = -1.0 Vdc) V <sub>CE</sub> = -1.0 Vdc) V <sub>CE</sub> = -1.0 Vdc) c, V <sub>CE</sub> = -1.0 Vdc)	h <sub>FE</sub>	60 80 100 60 30	- 300 - -	_	
Collector – Emitter $(I_C = -10 \text{ mAdc}, (I_C = -50 \text{ mAdc},$	$I_B = -1.0 \text{ mAdc}$	V <sub>CE</sub> (sat)	- -	-0.25 -0.4	Vdc	
Base – Emitter Saturation Voltage ( $I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ( $I_C = -50$ mAdc, $I_B = -5.0$ mAdc)		V <sub>BE(sat)</sub>	-0.65 -	-0.85 -0.95	Vdc	
SMALL-SIGNAL	. CHARACTERISTICS	<u> </u>				
Current - Gain - Ba	andwidth Product	f <sub>T</sub>	250	-	MHz	
Output Capacitano	e	C <sub>obo</sub>	bo - 4.5			
Input Capacitance		C <sub>ibo</sub>	- 10.0		pF	
Input Impedance (V <sub>CE</sub> = -10 Vdc,	I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>ie</sub>	2.0 12		kΩ	
Voltage Feedback (V <sub>CE</sub> = -10 Vdc,	Ratio I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>re</sub>	h <sub>re</sub> 0.1		X 10 <sup>-2</sup>	
Small – Signal Curr (V <sub>CE</sub> = -10 Vdc,	rent Gain I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>fe</sub>	100	400	-	
Output Admittance (V <sub>CE</sub> = -10 Vdc,	I <sub>C</sub> = -1.0 mAdc, f = 1.0 kHz)	h <sub>oe</sub>	3.0	60	μmhos	
Noise Figure NF $(V_{CE}=-5.0~Vdc,~I_{C}=-100~\mu Adc,~R_{S}=1.0~k~\Omega,~f=1.0~kHz)$				4.0	dB	
SWITCHING CHA	ARACTERISTICS					
Delay Time	(V <sub>CC</sub> = -3.0 Vdc, V <sub>BE</sub> = 0.5 Vdc)	t <sub>d</sub>	-	35	35 ns	
Rise Time	$(I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	t <sub>r</sub>	-	35		
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	= -10 mAdc) t <sub>s</sub> -		225		
Fall Time	$(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	t <sub>f</sub>	_	75	ns	

Fall Time  $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$ 2. Pulse Test: Pulse Width  $\leq 300 \mu \text{s}$ ; Duty Cycle  $\leq 2.0\%$ .



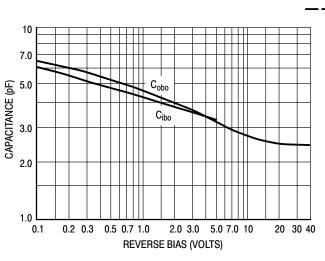
\* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

#### TYPICAL TRANSIENT CHARACTERISTICS

500



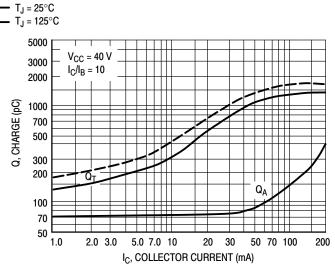
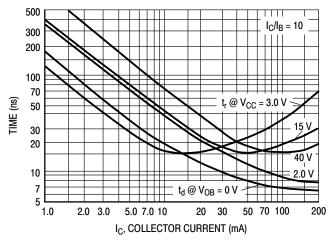


Figure 3. Capacitance

Figure 4. Charge Data



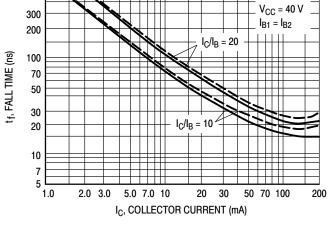
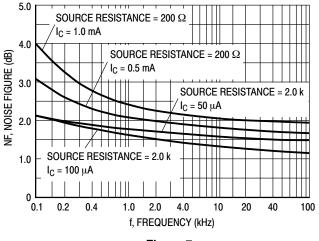


Figure 5. Turn - On Time

Figure 6. Fall Time

# TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$ 



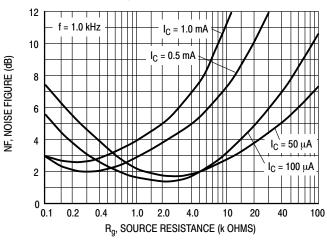
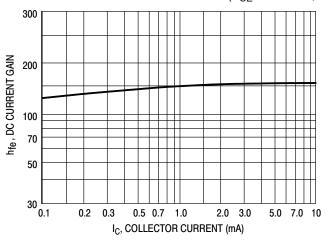


Figure 7.

Figure 8.

#### **h PARAMETERS**

 $(V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$ 



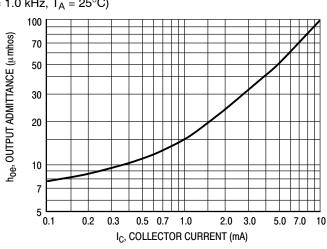
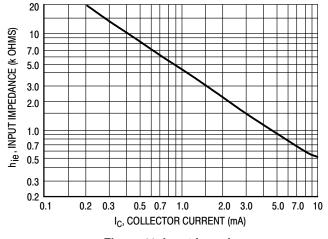


Figure 9. Current Gain

Figure 10. Output Admittance



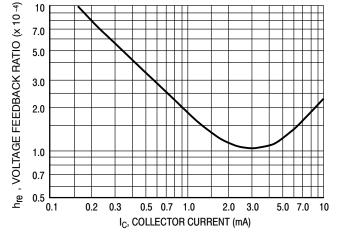


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

#### TYPICAL STATIC CHARACTERISTICS

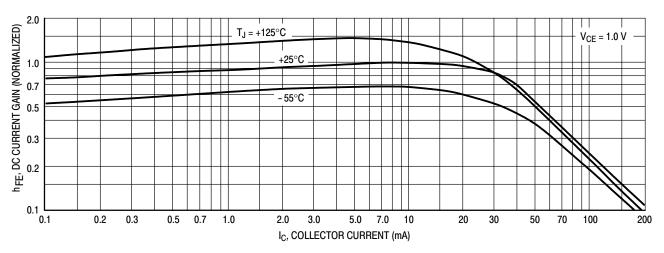


Figure 13. DC Current Gain

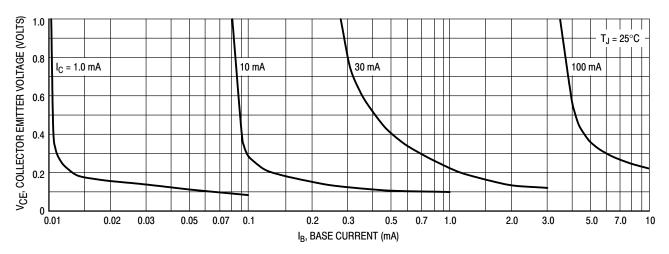


Figure 14. Collector Saturation Region

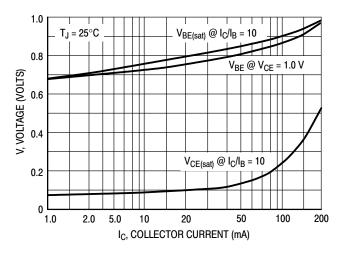


Figure 15. "ON" Voltages

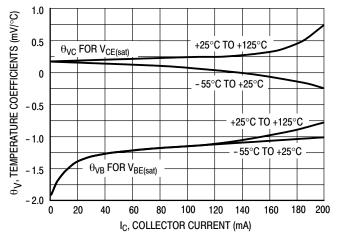


Figure 16. Temperature Coefficients

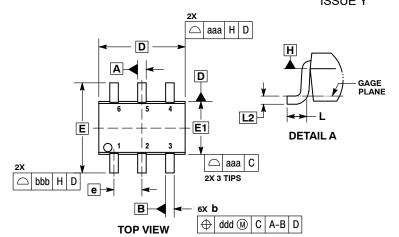
### **DEVICE ORDERING INFORMATION**

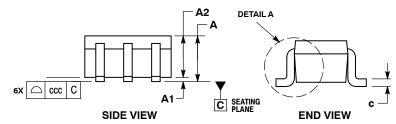
Device	Marking	Pin Out	Package	Shipping <sup>†</sup>
MBT3906DW1T1G	A2	6 5 4 1 2 3	SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW1T1G	A2	6 5 4	SOT-363 (Pb-Free)	3000 / Tape & Reel
SMBT3906DW3T1G	A3	6 5 4	SOT-363 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

#### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**



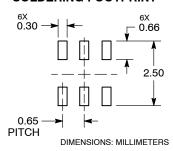


- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRU-SIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF
- THE PLASTIC BODY AND DATUM H.
  DATUMS A AND B ARE DETERMINED AT DATUM H.

- DATUMS A AND B ARE DETERMINED AT DATUM H.
  DIMENSIONS b AND 6 APPLY TO THE FLAT SECTION OF THE
  LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
  DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION.
  ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN
  EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10				0.004	

#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2

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